

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT3950153

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DARRELL EUGENE TINKER	07/06/2016
RECEIVING PARTY DATA	
Name:	TEMPO SEMICONDUCTOR, LLC
Street Address:	8627 N. MO PAC EXPRESSWAY
Internal Address:	SUITE 130
City:	AUSTIN
State/Country:	TEXAS
Postal Code:	78759
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15203393
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 4:	DRIFTWOOD, TEXAS 78619
ATTORNEY DOCKET NUMBER:	JTS010-01
NAME OF SUBMITTER:	JEFFREY VAN MYERS
SIGNATURE:	/Jeffrey Van Myers/
DATE SIGNED:	07/06/2016
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 1	
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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I,

Darrell Eugene Tinker	Austin	Texas, USA
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have sold, assigned and transferred, and do hereby sell, assign and transfer unto Tempo Semiconductor, Inc., a corporation of the State of Texas, having its principal office at 8627 N. Mo Pac Expressway, Suite 130, Austin, TX 78759, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in:

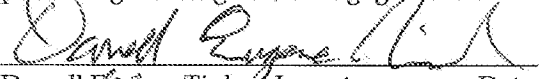
Method and Apparatus for Generating Harmonics Using Polynomial Non-Linear Functions

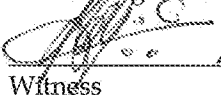
described, illustrated and claimed in an Application for Patent of the United States of America executed by me of even date herewith, together with the entire right, title and interest in and to said Application, and in and to Letters Patent which may be issued upon any Application for Letters Patent based on said Application, and upon any division, extension, continuation, or reissue of any such Application.

I hereby also sell, assign and transfer unto said Tempo Semiconductor, Inc., the entire right, title and interest in and to said invention, and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of said inventions and said applications for Letters Patent in foreign countries, and I further authorize said Tempo Semiconductor, Inc., to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of said application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby authorize and request the Commissioner for Patents of the United States of America to issue Letters Patent that may result from the timely filing of an Application for Letters Patent based on the aforesaid Application, as well as any division, extension, continuation or reissue of any such Application, to said Tempo Semiconductor, Inc., for the sole use and behoof of said Tempo Semiconductor, Inc., its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to said Tempo Semiconductor, Inc.

I agree that, when requested, I will, without charge to Tempo Semiconductor, Inc., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for said inventions in any and all countries and for vesting title thereto in said Tempo Semiconductor, Inc., its successors, assigns and legal representatives or nominees. I covenant with said Tempo Semiconductor, Inc., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

 July 6, 2016
Darrell Eugene Tinker, Inventor Date

 K. GOZIE JESINA CHUKWURA
Witness Date

July 6/2016